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PATENT NUMBER and ISSUE DATE

U.S. **UTILITY** Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10081491	02/22/2002	438	108	2812	Roman

**APPLICANTS: Pendse Rajendra; Ahmad Nazir; Chen Andrea; Kim Kyung-Moon; Kweon Young-Do; Tam Samuel;

**CONTINUING DATA VERIFIED: YES AR 10/30/02
THIS APPLN CLAIMS BENEFIT OF 60/272,237 02/27/2001

** FOREIGN APPLICATIONS VERIFIED: NO AR 10/30/02

PG-PUB DO NOT PUBLISH ☐	RESCIND ☐	
Foreign priority claimed ☐ yes ☒ no 35 USC 119 conditions met ☐ yes ☒ no Verified and Acknowledged Examiners's intials AR 10/30/02		ATTORNEY DOCKET NO CPAC 1008-2 US

TITLE : Chip scale package with flip chip interconnect

U.S.DEPT. OF COMM./PAT.& TM-PTO-436L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED	Assistant Examiner	CLAIMS ALLOWED Total Claims / Print Claim for O.G
ISSUE FEE Amount Due / Date Paid	Primary Examiner	DRAWING Sheets Drwg. / Figs.Drwg. / Print Fig.
☐ TERMINAL DISCLAMER	PREPARED FOR ISSUE	Applicati n Examiner

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